

MAC97A6S,MAC97A6M Series

- Description:**

Logic level sensitive gate triac intended to interfaced directly to microcontrollers,logic integrated circuits and other low power gate trigger circuits.

- Applications**

This device is suitable for low power AC switching application,phase control application such as fan speed and temperature modulation control,lighting control and static switching relay.

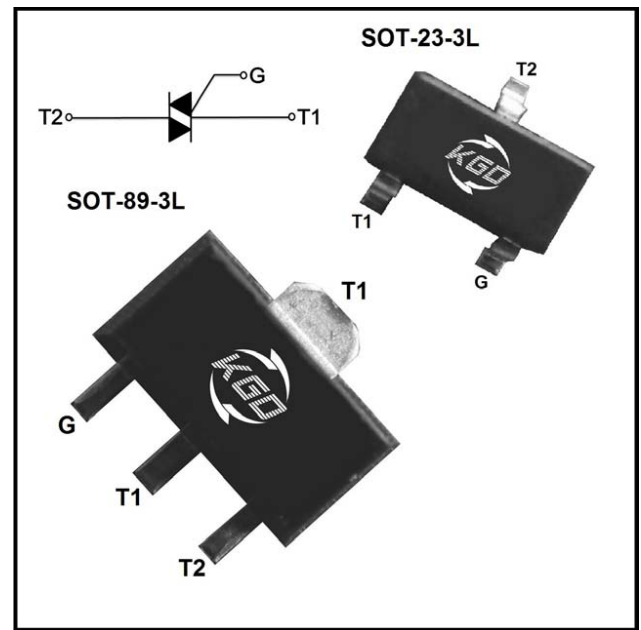
- Features:**

Blocking voltage to 600V

On-state RMS current to 0.8A

Non-repetitive peak on-state current to 8A

- Absolute Maximum Ratings**



Symbol	Parameter	Conditions	Value	Unit	
V_{DRM}	Repetitive peak off-state voltage	$T_J=25^{\circ}C$	600	V	
V_{RRM}	Repetitive peak Reverse voltage	$T_J=25^{\circ}C$	600	V	
$I_{T(RMS)}$	RMS on-state current (full sine wave)	$T_c=110^{\circ}C$	0.8	A	
$I_{T(av)}$	Average on-state current (full sine wave)	$T_c=110^{\circ}C$	0.5	A	
I_{TSM}	Non-repetitive surge peak On-state current (One full cycle,sine wave, $T_c=110^{\circ}C$)	$t_p=10ms$	8	A	
		$t_p=8.3ms$	8.3		
I^2t	I^2t Value for fusing	$t_p=10ms$	0.32	A^2S	
I_{GM}	Peak gate current	$t_p \leq 2\mu s, T_J=80^{\circ}C$	1	A	
$P_{G(AV)}$	Average gate power dissipation	$t_p \leq 10ms, T_J=80^{\circ}C$	0.1	W	
PGM	Peak gate power dissipation		1	W	
T_{STG}	Storage temperature		-40	150	$^{\circ}C$
T_J	Junction temperature		-40	125	$^{\circ}C$

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Electrical Characteristics

Symbol	Conditions	Quadrant	Value		Unit
			MIN	MAX	
I_{GT}	$V_D=12V, R_L=33\Omega$	I - II -III	/	4	mA
		IV	/	6	
V_{GT}		ALL	/	1.5	V
V_{GD}	$V_D=V_{DRM}, R_L=3.3K\Omega, T_J=125^\circ C$	ALL	0.2	/	V
I_L	$I_G=1mA$	ALL	/	10	mA
I_H	$I_T=200mA$		/	5	mA
dV/dt	$V_{DM}=67\%V_{DRM}$, gate open, $T_J=125^\circ C$		25	/	V/ μs
$(dV/dt)_c$	$(dI/dt)_c=0.3A/ms, T_J=125^\circ C$		0.5	/	V/ μs

Electrical Characteristics

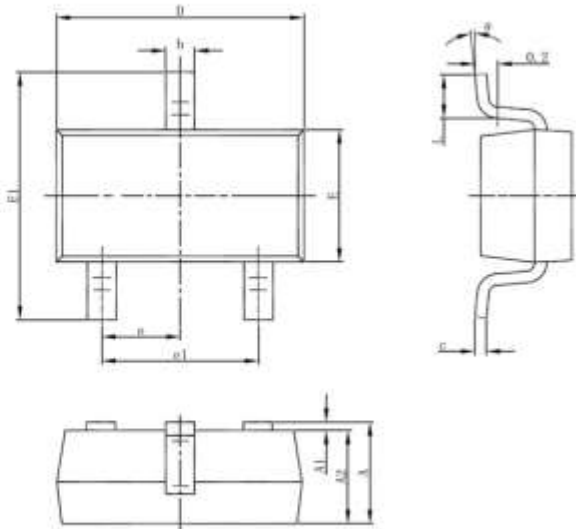
Symbol	Parameter	Numerical	Unit
V_{TM}	$I_T=1.1A, t_p=380\mu s$ $T_J=25^\circ C$	1.5	V
I_{DRM}	$T_J=25^\circ C$	5	μA
I_{RRM}	$V_D=V_{DRM}, V_R=V_{RRM}$ $T_J=125^\circ C$	0.1	mA

Thermal Characteristics

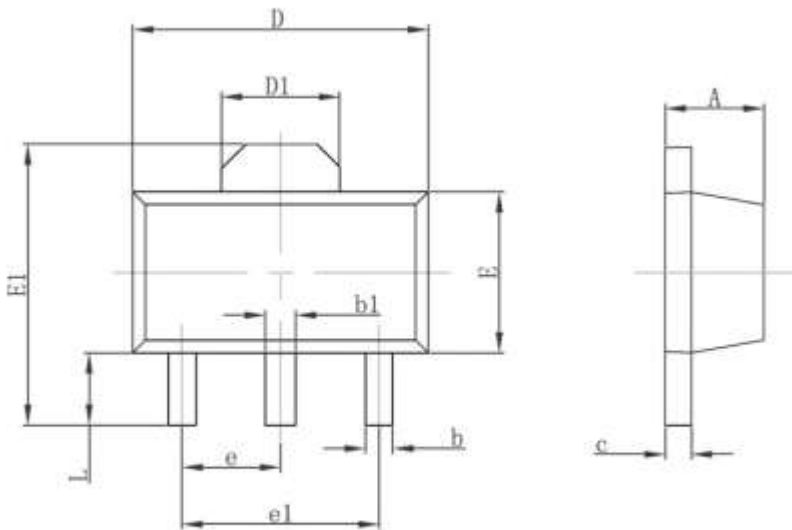
Symbol	Parameter	Numerical(MAX)	Unit
$R_{th(j-c)}$	Junction to case	15	$^\circ C/W$
$R_{th(j-a)}$	Junction to ambient	150	$^\circ C/W$
T_L	Lead Solder Temperature(<1/16" from case, 10 secs max)	260	$^\circ C$

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● Package Outline Dimensions

SOT-23-3L


Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950		0.037	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

SOT-89-3L


Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.400	1.600	0.055	0.063
b	0.320	0.520	0.013	0.020
b1	0.400	0.580	0.016	0.023
c	0.350	0.440	0.014	0.017
D	4.400	4.600	0.173	0.181
D1	1.550 REF.		0.061 REF.	
E	2.300	2.600	0.091	0.102
E1	3.940	4.250	0.155	0.167
e	1.500 TYP.		0.060 TYP.	
e1	3.000 TYP.		0.188 TYP.	
L	0.900	1.200	0.035	0.047

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FIG.1: Maximum power dissipation versus average on-state current.

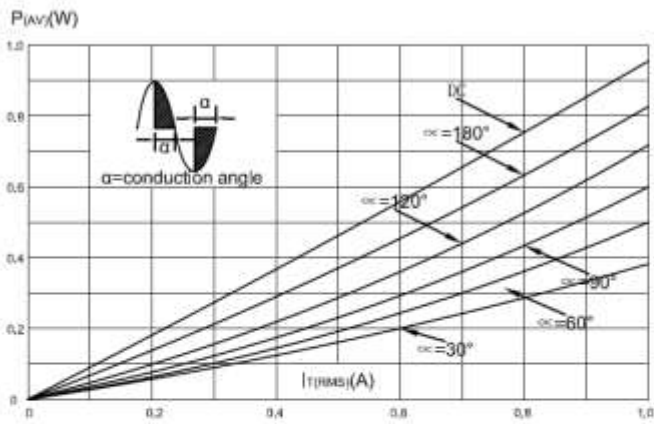


FIG.2: RMS on-state current versus case temperature.

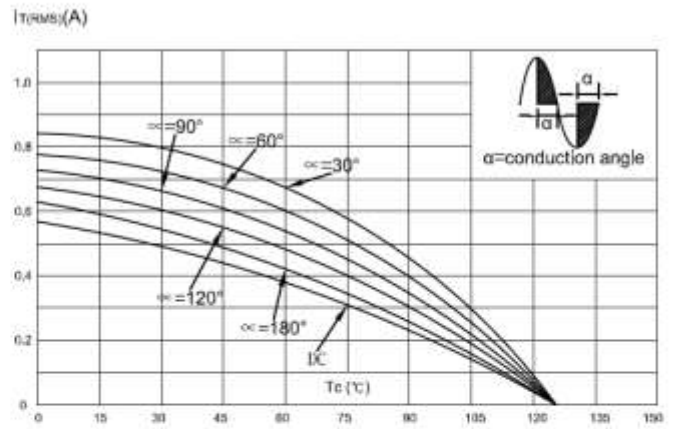


FIG.3: On-state characteristics (maximum values)

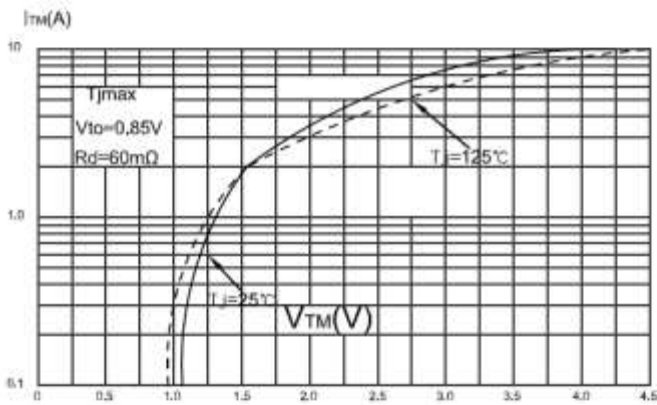


FIG.4: Surge peak on-state current versus number of cycles.

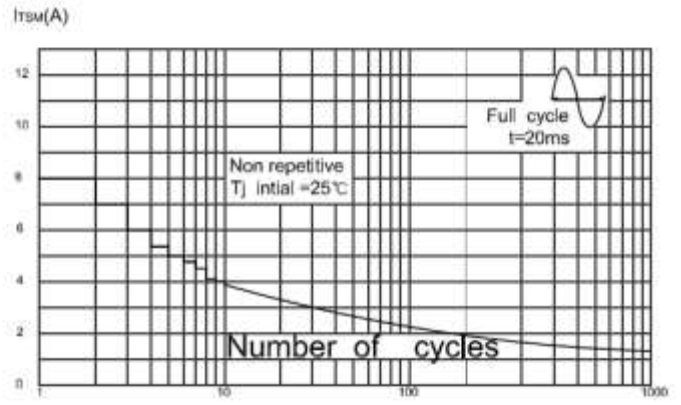


FIG.5: Relative variation of gate trigger current, holding current and latching current versus junction temperature (typical values).

